## Maximum Ratings (@$T_A$ = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|---|---|---|---|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | $V_{RRM}$<br>$V_{RWM}$<br>$V_{RM}$ | 40 | V |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 28 | V |
| Average Rectified Output Current (See Figure 1) | $I_O$ | 2.0 | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms<br>Single Half Sine-Wave Superimposed on Rated Load | $I_{FSM}$ | 50 | A |
| Repetitive Peak Avalanche Power (1µs, +25°C) | $P_{ARM}$ | 6,000 | W |

## Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|---|---|---|
| Maximum Thermal Resistance | | | |
| Thermal Resistance Junction to Soldering (Note 7) | $R_{\theta JS}$ | 5 | °C/W |
| Thermal Resistance Junction to Ambient (Note 8) | $R_{\theta JA}$ | 180 | |
| Thermal Resistance Junction to Ambient (Note 9) | $R_{\theta JA}$ | 115 | |
| Thermal Resistance Junction to Lead (Note 8) | $R_{\theta JL}$ | 60 | |
| Operating and Storage Temperature Range | $T_J$, $T_{STG}$ | -65 to +150 | °C |

## Electrical Characteristics (@$T_A$ = +25°C unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|---|---|---|---|---|---|
| Reverse Breakdown Voltage | $V_{(BR)R}$ | 40 | - | - | V | $I_R$ = 100µA |
| Forward Voltage Drop | $V_F$ | - | 0.265 | 0.315 | V | $I_F$ = 0.1A, $T_J$ = +25°C |
| | | - | 0.38 | 0.43 | | $I_F$ = 1.0A, $T_J$ = +25°C |
| | | - | 0.45 | 0.50 | | $I_F$ = 2.0A, $T_J$ = +25°C |
| | | - | 0.17 | 0.22 | | $I_F$ = 0.1A, $T_J$ = +125°C |
| | | - | 0.325 | 0.375 | | $I_F$ = 1.0A, $T_J$ = +125°C |
| | | - | 0.42 | 0.47 | | $I_F$ = 2.0A, $T_J$ = +125°C |
| Leakage Current (Note 10) | $I_R$ | - | 8 | 40 | µA | $V_R$ = 5V, $T_J$ = +25°C |
| | | - | 16 | 100 | µA | $V_R$ = 40V, $T_J$ = +25°C |
| | | - | 1.3 | 8 | mA | $V_R$ = 5V, $T_J$ = +125°C |
| | | - | 2.1 | 10 | mA | $V_R$ = 40V, $T_J$ = +125°C |

Notes:
7. Theoretical $R_{\theta JS}$ calculated from the top center of the die straight down to the PCB cathode tab solder junction.
8. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
9. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
10. Short duration pulse test used to minimize self-heating effect.

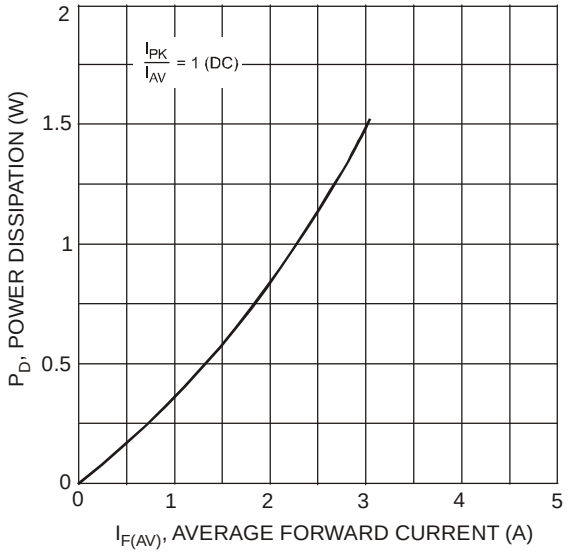


Fig. 1 Forward Power Dissipation

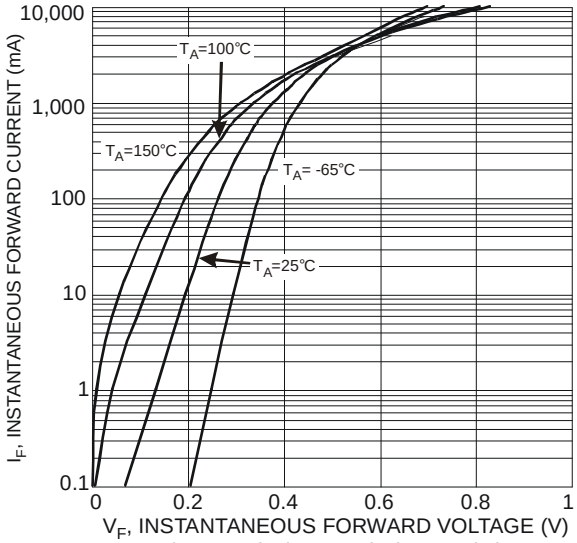


Fig. 2 Typical Forward Characteristics

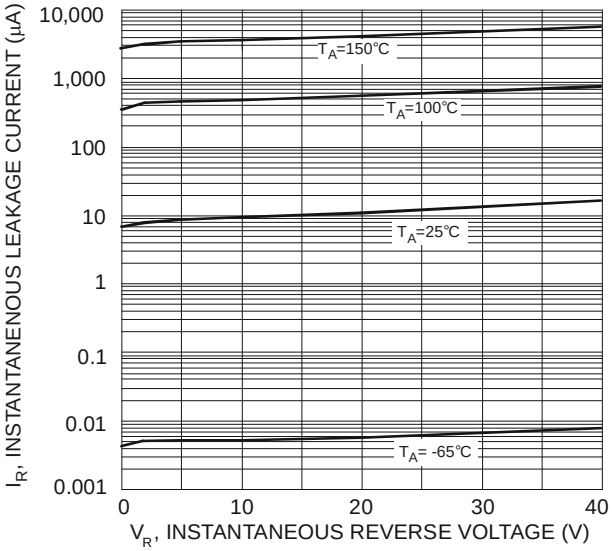


Fig. 3 Typical Reverse Characteristics

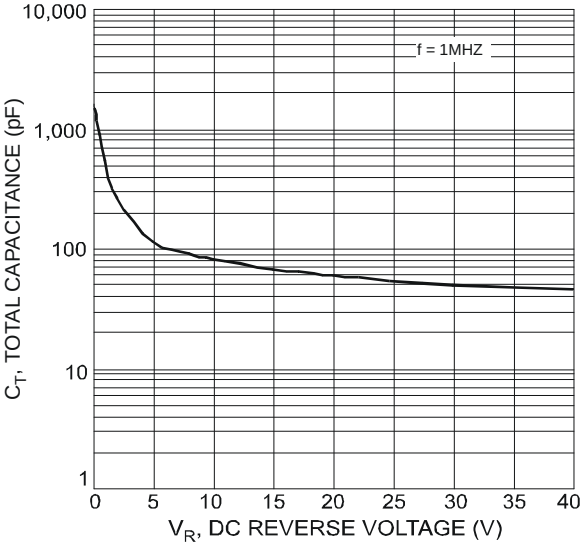


Fig. 4 Total Capacitance vs. Reverse Voltage

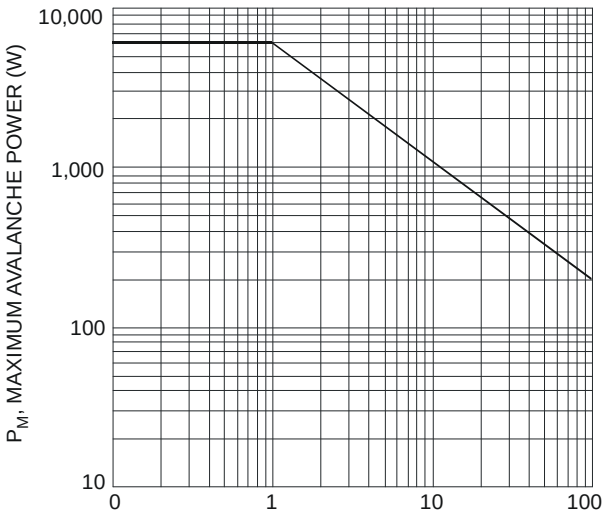



Fig. 5 Maximum Avalanche Power vs. Pulse Duration

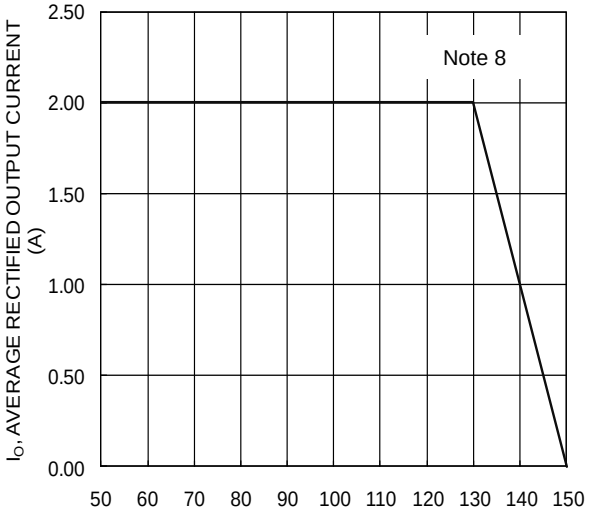



Figure 6. DC Forward Current Derating

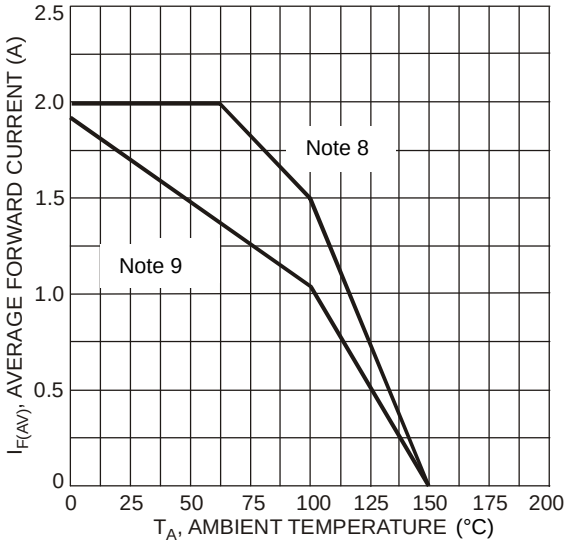



Fig. 7 Forward Current Derating Curve

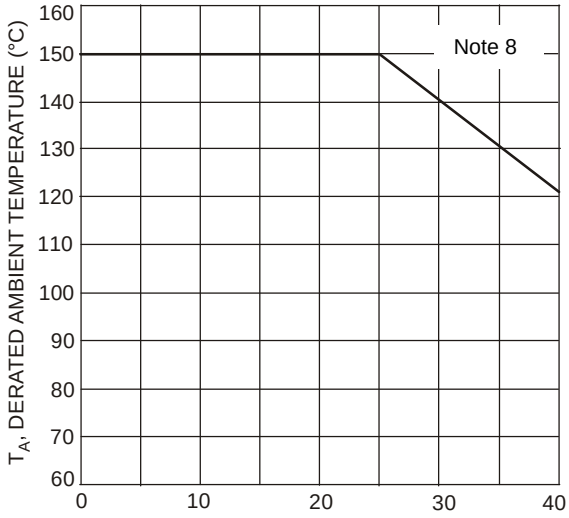



Fig. 8 Operating Temperature Derating

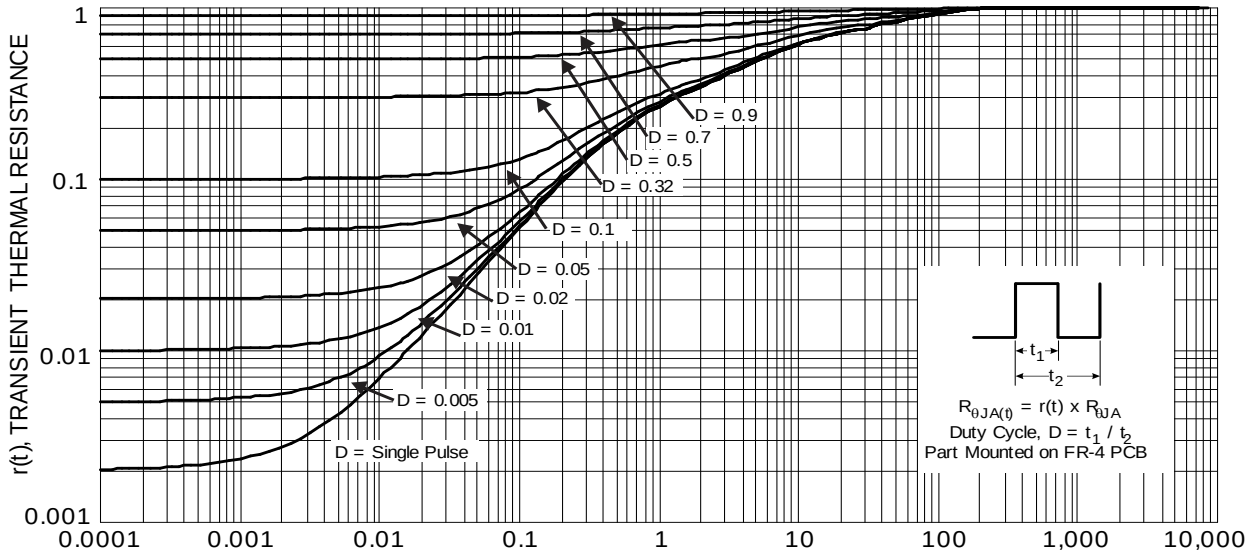
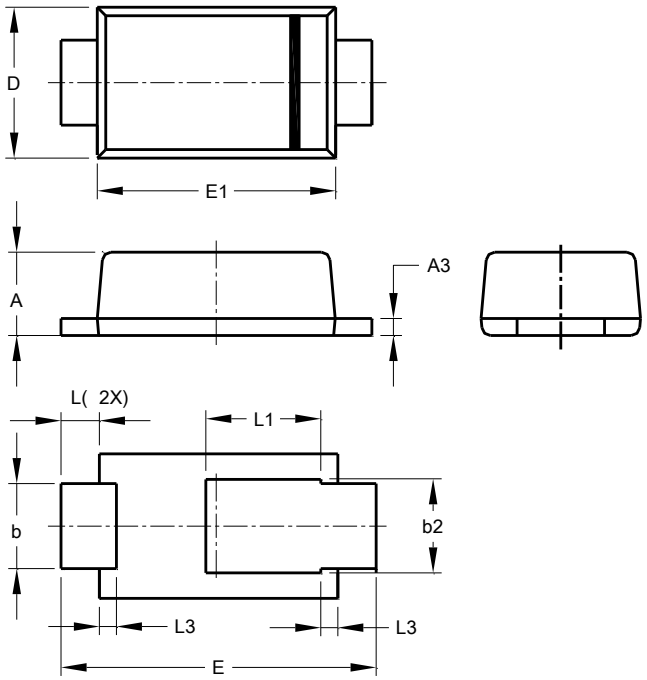



Fig. 9 Transient Thermal Resistance

## Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

**PowerDI123**

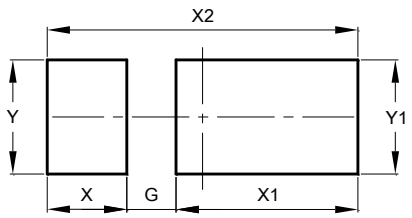



| PowerDI123 | | | |
|---|---|---|---|
| **Dim** | **Min** | **Max** | **Typ** |
| **A** | 0.93 | 1.00 | 0.98 |
| **A3** | 0.15 | 0.25 | 0.20 |
| **b** | 0.85 | 1.25 | 1.00 |
| **b2** | 1.025 | 1.125 | 1.10 |
| **D** | 1.63 | 1.93 | 1.78 |
| **E** | 3.50 | 3.90 | 3.70 |
| **E1** | 2.60 | 3.00 | 2.80 |
| **L** | 0.40 | 0.50 | 0.45 |
| **L1** | 1.25 | 1.40 | 1.35 |
| **L3** | 0.125 | 0.275 | 0.20 |
| **All Dimensions in mm** | | | |

## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

**PowerDI123**




| Dimensions | Value (in mm) |
|---|---|
| **G** | 0.65 |
| **X** | 1.05 |
| **X1** | 2.40 |
| **X2** | 4.10 |
| **Y** | 1.50 |
| **Y1** | 1.50 |

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